## Si Substrate Orientation Dependence of Ferroelectric HfO<sub>2</sub> Properties Deposited by RF Magnetron Sputtering Tokyo Institute of Technology<sup>1</sup>, °Min Gee Kim<sup>1</sup>, Shun-ichiro Ohmi<sup>1</sup> E-mail: kim.m.ak@m.titech.ac.jp, ohmi@ee.e.titech.ac.jp.

Ferroelectric  $HfO_2$  is receiving great attention for one-transistor type ferroelectric random access memory. Although it was reported that undoped  $HfO_2$  exhibits orthorhombic phase [1,2], which is ferroelectric phase of  $HfO_2$ , direct deposition with orthorhombic phase on Si substrates is necessary to be investigated. The crystallinity of  $HfO_2$  should depend on the Si orientation. In this research, the growth of orthorhombic  $HfO_2$  on Si(100) and Si(111) substrates and electrical characteristics were investigated.

After p-Si(100) and p-Si(111) substrates were cleaned by SPM ( $H_2SO_4:H_2O_2=4:1$ ) and DHF ( $HF:H_2O=1:100$ ) solutions, the 24 nm-thick HfO<sub>2</sub> film was directly deposited by RF magnetron sputtering at room temperature. The flow ratio was  $Ar/O_2 = 2/1$  sccm with gas pressure of 0.4 Pa. Then, post deposition annealing (PDA) was carried out at 600°C for 30 s to crystallize the film. Finally, Al as top and bottom electrodes were deposited by thermal evaporation. The fabricated diodes were measured by C-V and J-V.

Figure 1 shows C-V and J-V characteristics of the diodes. Smaller capacitance in the Al/HfO<sub>2</sub>/p-Si(111) diode indicates that thicker interfacial layer was formed than that of Al/HfO<sub>2</sub>/Si(100), as shown in Fig. 1(a). The leakage current was almost same for both diodes as shown in Fig. 1(b). Although the effective electric field applied for the HfO<sub>2</sub> film on p-Si(111) substrate was smaller, the memory window of 0.45 V was obtained in the Al/HfO<sub>2</sub>/p-Si(111) diode, while it was 0.39 V in case of Al/HfO<sub>2</sub>/p-Si(100) diode at the same operating voltage. This results suggested that crystallinity was improved in case of the HfO<sub>2</sub> deposited on the Si(111) substrate.



Fig. 1. (a) C-V and (b) J-V characteristics of the Al/HfO<sub>2</sub>/p-Si(100) and Al/HfO<sub>2</sub>/p-Si(111) diodes.

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